

## **Bill of Materials**

Number		Value	Description	Part Number	Part Reference	MPN	NOTE Status	Manufacturer	PCB Packa
1	. 0	DNM	CAPACITOR, CERAMIC, N/A VALUE, -55DEGC/+125DEGC, 0402, SMD	02-04164	ANT1 C12 C41 C177 C302	CAPACITOR_0402_DNM_N/A_M	PREFERRED	Manufacturer selection	0402
2	2	1pF	CAPACITOR, CERAMIC COG/NPO, 1pF, 50V, -0.1pF/+0.1pF, - 55DEGC/+125DEGC, 0402, SMD	02-04367	ANT2 C176	GRM1555C1H1R0BA01D	PREFERRED	MURATA	0402
3	5	12nH	INDUCTOR, CHIP, 12nH, -5%/+5%, 0.5A, -55DEGC/+125DEGC, 0402, SMD	03-06556	ANT3 L174 L192 L193 L201	LQW15AN12NJ00D	PREFERRED	MURATA	0402
4	11	47nF	CAPACITOR, CERAMIC, X7R, 47nF, 25V, -10%/+10%, - 55DEGC/+125DEGC, 0402, SMD	02-04324	C11 C51 C121 C131 C151 C221 C251 C261 C271 C281 C291	. GRM155R71E473KA88D	PREFERRED	MURATA	0402
5	1	2.2uF	CAPACITOR, CERAMIC X5R, 2.2uF, 10V, -10%/+10%, - 55DEGC/+85DEGC, 0603, SMD	02-02405	C52	GRM188R61A225KE34D	PREFERRED	MURATA	0603
6	1	220nF	CAPACITOR, CERAMIC XSR, 220nF, 10V, -15%/+15%, - 55DEGC/+85DEGC, 0402, SMD	02-04353	C61	GRM155R61A224KE19D	PREFERRED	MURATA	0402
7	2	2 10nF	CAPACITOR, CERAMIC X7R, 10nF, 25V, -10%/+10%, - 55DEGC/+125DEGC, 0402, SMD	02-02314	C171 C211	GRM155R71E103KA01D	PREFERRED	MURATA	0402
8	1	100pF	CAPACITOR, CERAMIC COG/NPO, 100pF, 50V, -5%/+5%, - 55DEGC/+125DEGC, 0402, SMD	02-04365	C172	GRM1555C1H101JA01D	PREFERRED	MURATA	0402
9	1	. 33pF	CAPACITOR, CERAMIC COG/NPO, 33pF, 50V, -5%/+5%, - 55DEGC/+125DEGC, 0402, SMD	02-04354	C173	GRM1555C1H330JA01D	PREFERRED	MURATA	0402
10	3	15pF	CAPACITOR, CERAMIC COG/NPO, 15pF, 50V, -5%/+5%, - 55DEGC/+125DEGC, 0402, SMD	02-04372	C174 C301 C311	GRM1555C1H150JA01D	PREFERRED	MURATA	0402
11	. 1	3pF	CAPACITOR, CERAMIC COG/NPO, 3pF, 50V, -0.25pF/+0.25pF, - 55DEGC/+125DEGC, 0402, SMD	02-04606	C175	GRM1555C1H3R0CA01D	PREFERRED	MURATA	0402
12	1	2.2pF	CAPACITOR, CERAMIC COG/NPO, 2.2pF, 50V, -0.25pF/+0.25pF, - 55DEGC/+125DEGC, 0402, SMD	02-04605	C181	GRM1555C1H2R2CA01D	PREFERRED	MURATA	0402
13	2	3.3pF	CAPACITOR, CERAMIC COG/NPO, 3.3pF, 50V, -0.25pF/+0.25pF, - 55DEGC/+125DEGC, 0402, SMD	02-04369	C191 C201	GRM1555C1H3R3CA01D	PREFERRED	MURATA	0402
14	1	1.5nF	CAPACITOR, CERAMIC U2J, 1.5nF, 10V, -5%/+5%, - 55DEGC/+125DEGC, 0402, SMD	02-04545	C231	GRM1557U1A152JA01D	PREFERRED	MURATA	0402
15	0	DNM	CAPACITOR, CERAMIC X7R, 100nF, 10V, -10%/+10%, - 55DEGC/+125DEGC, 0402, SMD	02-00760	C321	GRM155R71A104KA01D	PREFERRED	MURATA	0402
16	0	DNM	CAPACITOR, CERAMIC COG/NPO, 22pF, 50V, -5%/+5%, - 55DEGC/+125DEGC, 0402, SMD	02-04373	C322	GRM1555C1H220JA01D	PREFERRED	MURATA	0402
17	1	BLM15HG102SN1	FILTER, INDUCTOR TYPE, 1000OHM@100MHZ, 25%,250mA, 0402, SMD	04-00032	L1	BLM15HG102SN1D	PREFERRED	MURATA	0402
18	1	10nH	INDUCTOR, CHIP, 10nH, -5%/+5%, 0.5A, -55DEGC/+125DEGC, 0402, SMD	03-06552	L171	LQW15AN10NJ00D	PREFERRED	MURATA	0402
19	1	7.5nH	INDUCTOR, CHIP, 7.5nH, -2%/+2%, 0.57A, -55DEGC/+125DEGC, 0402, SMD	03-06551	L172	LQW15AN7N5G00D	PREFERRED	MURATA	0402
20	1	18nH	INDUCTOR, CHIP, 18nH, -5%/+5%, 0.37A, -55DEGC/+125DEGC, 0402, SMD	03-06593	L173	LQW15AN18NJ00D	PREFERRED	MURATA	0402
21	1	15nH	INDUCTOR, CHIP, 15nH, -5%/+5%, 0.46A, -55DEGC/+125DEGC, 0402, SMD	03-06555	L191	LQW15AN15NJ00D	PREFERRED	MURATA	0402
22	2	? SFM-110-02-S-D-A-K-TR	CONNECTOR, HEADER, FEMALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 1.27mm, SMD	06-02251	P1 P2	SFM-110-02-SM-D-A-K-TR	PREFERRED	SAMTEC	
23		SMA-10V21-TGG	CONNECTOR, COAX RF, STRAIGHT, FEMALE, 1 PIN, SMD	06-02188	P3	SMA-10V21-TGG	PREFERRED	HUS-TSAN	
24		0	RESISTOR, JUMPER, -55DEGC/+155DEGC, 0402, SMD	01-01784	R12	RK73Z1ETTP	PREFERRED	KOA SPEER	0402
25		. 56k	RESISTOR, THICK FILM, 56k, -1%/+1%, 0.063W, 50V, - 55DEGC/+155DEGC, 0402, SMD	01-16848	R141	RK73H1ETTP5602F	PREFERRED	KOA SPEER	0402
26		10	RESISTOR, THICK FILM, 10, -5%/+5%, 0.063W, 50V, - 55DEGC/+155DEGC, 0402, SMD	01-11612	R171	RESISTOR_0402_10_+/- 5%_50V_0.063W_M_+/-200PPM	PREFERRED	Manufacturer selection	0402
27	1	0	RESISTOR, JUMPER, 3 PORTS, -55DEGC/+155DEGC, 0402, SMD	01-16574	R181	RK73Z1ETTP	PREFERRED	KOA SPEER	0402
28	0	DNM	RESISTOR, DO NOT MOUNT, 0402, SMD	01-02472	R321 R322	DNM	PREFERRED	DO NOT MOUNT	0402
29	0	DNM	IC, ANALOG, HIGH PSRR FAST RF LOW DROPOUT REGULATOR IN WAFER CHIP SCALE, VIN:2.7V TO 5.5V, VOUT: 3V, SOT23-5, SMD	18-01358	U2	TPS79330DBVR	NOT_PREFERRED	TEXAS INSTRUMENTS	SOT23-5



## **Bill of Materials**

Item Number	Quantity	Value	Description	Part Number	Part Reference	MPN	NOTE Status	Manufacturer	PCB Package
30	) 1	CC120xRHB	IC, ANALOG RF, CC120xRHB, N/A, QFN32, SMD	18-28112	U3	CC120xRHB	PREFERRED	TEXAS INSTRUMENTS	QFN32
3:	1 1		CRYSTAL, OSCILATOR, 40MHz, -15PPM/DEGC/+15PPM/DEGC, 100V, -20DEGC/+75DEGC, SMD	12-00469	X1	NX3225SA 40MHz EXS00A-CS03880		NIHON DEMPA KOGYO CO., LTD	
33	2 0		CRYSTAL, OSCILATOR, TBD, 2.3V TO 3.6V, -30DEGC/+85DEGC, , SMD	12-00451	X2	TG_5021CG	PREFERRED	Epson Toyocom	

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